



Material Content Data Sheet



Sales Product Name		BSS127 H6327		Issued		16. July 2019		
MA#		MA005351606						
Package		PG-SOT23-3-5		Weight*		9.34 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.04		382	
	noble metal	gold	7440-57-5	0.014	0.15		1480	
	inorganic material	silicon	7440-21-3	0.157	1.68	1.87	16776	18638
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		65	
	non noble metal	titanium	7440-32-6	0.003	0.03		322	
	non noble metal	chromium	7440-47-3	0.009	0.10		967	
	non noble metal	copper	7440-50-8	3.000	32.11	32.25	321110	322464
wire	non noble metal	copper	7440-50-8	0.008	0.08	0.08	842	842
encapsulation	organic material	carbon black	1333-86-4	0.057	0.61		6116	
	plastics	epoxy resin	-	1.229	13.15		131495	
	inorganic material	silicondioxide	60676-86-0	4.429	47.40	61.16	473991	611602
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	16015	16015
plating	noble metal	silver	7440-22-4	0.284	3.04	3.04	30439	30439
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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